

### ■ N-Channel Enhancement MOSFET

#### **Features**

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

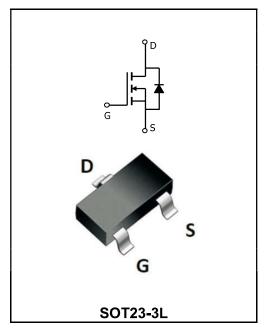
# **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

# **Description**

The YFW1002 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

VDSS	RDS(ON) @10V (typ)	<b>I</b> D
100V	185mΩ	2A



Marking Code				
YFW1002	1002K			

# Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I <sub>D</sub>	2	А
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	5	Α
Maximum Power Dissipation	P <sub>D</sub>	1.1	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### **Thermal Characteristic**

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Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\Theta JA}$	120	°C∕W



# **Electrical Characteristics Ta=25°C**

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	<u> </u>		•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.2	2.0	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, <b>I</b> <sub>D</sub> =1A	-	185	220	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =1A	1	-	-	S
Dynamic Characteristics (Note4)	<u> </u>		•			
Input Capacitance	C <sub>lss</sub>	\/ 50\/\/ 0\/	-	190	-	PF
Output Capacitance	Coss	$V_{DS}=50V, V_{GS}=0V,$ F=1.0MHz	-	22	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	1 – 1.0IVII IZ	-	13	-	PF
Switching Characteristics (Note 4)		•				
Turn-on Delay Time	t <sub>d(on)</sub>		-	6	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =50V, $I_{D}$ =1.3A, $R_{L}$ =39 $\Omega$	-	10	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =1 $\Omega$	-	10	-	nS
Turn-Off Fall Time	t <sub>f</sub>	]	-	6	-	nS
Total Gate Charge	Qg	V -50VI -4.2A	-	5.2		nC
Gate-Source Charge	Q <sub>gs</sub>	- V <sub>DS</sub> =50V,I <sub>D</sub> =1.3A,	-	0.75	-	nC
Gate-Drain Charge	$Q_{gd}$	- V <sub>GS</sub> =10V	-	1.4	-	nC
Drain-Source Diode Characteristics			•	•		
Diode Forward Voltage (Note 3)	$V_{SD}$	V <sub>GS</sub> =0V,I <sub>S</sub> =1.3A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	2	Α

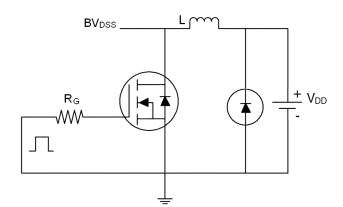
# Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

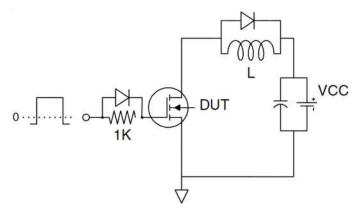


# **Test Circuit**

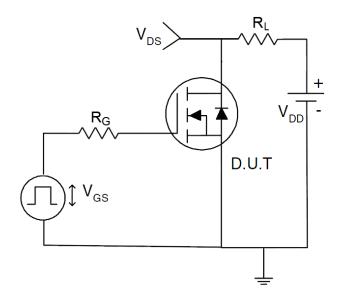
# 1) E<sub>AS</sub> test circuit



# 2) Gate charge test circuit

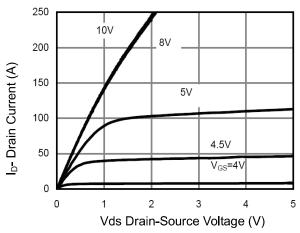


### 3) Switch Time Test Circuit

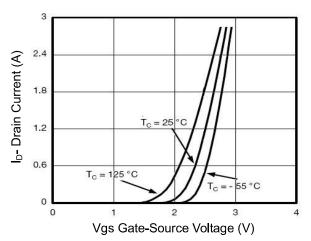




# **Ratings and Characteristic Curves**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

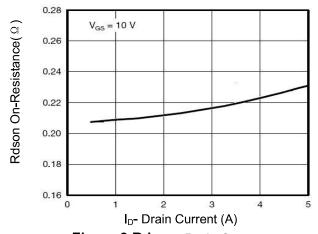


Figure 3 Rdson- Drain Current

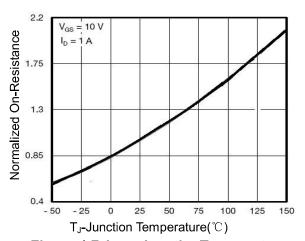


Figure 4 Rdson-JunctionTemperature

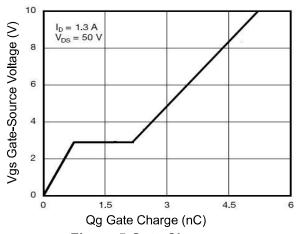


Figure 5 Gate Charge

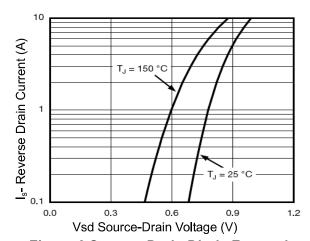


Figure 6 Source- Drain Diode Forward



### **Ratings and Characteristic Curves**

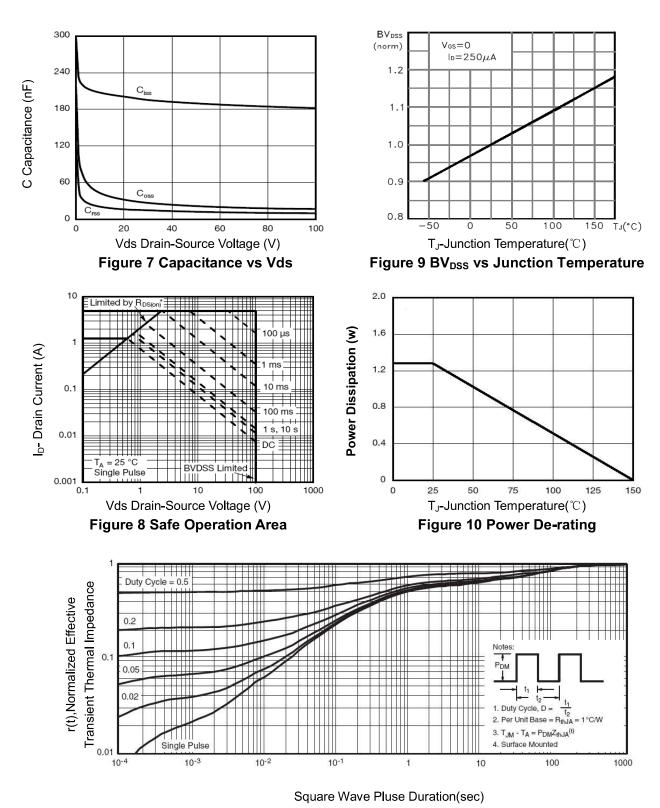


Figure 11 Normalized Maximum Transient Thermal Impedance

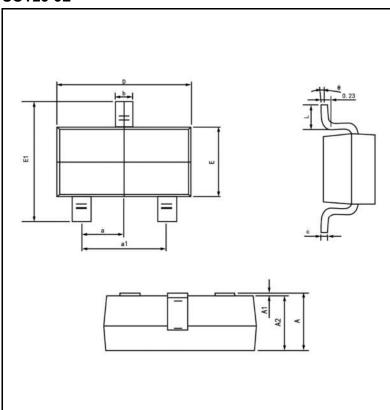


# **Ordering information**

Package	Packing Description	Base Quantity	Packing Quantity
SOT23-3L	Tape/Reel,7"reel	3000pcs/Reel	24000PCS/Box 120000PCS/Carton

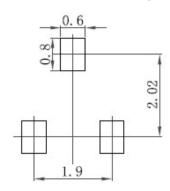
# **Package Dimensions**

# SOT23-3L



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Dim.	Millimeter (mm)		n	mil	
	Min.	Max.	Min.	Max.	
Α	1.05	1.25	41	49.2	
A1	0.	10	3.	93	
A2	1.05	1.15	41	45	
b	0.30	0.50	12	20	
С	0.10	0.20	3.93	7.9	
D	2.82	3.02	111	119	
E	1.50	1.70	59	67	
E1	2.65	2.95	104	116	
е	0.95		37	7.4	
e1	1.80	2.00	71	78	
L	0.30	0.066	12	26	
Θ	8°				

The recommended mounting pad size





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